

Agilent HDMP-0552 Quad Port Bypass Circuit with CDR and Data Valid Detection

For Fibre Channel Arbitrated Loops Data Sheet

Description

The HDMP-0552 is a Quad Port Bypass Circuit (PBC) with Clock and Data Recovery (CDR) and data valid detection capability included. See Figure 1 for block diagram. This device minimizes part count, cost and jitter accumulation while repeating incoming signals. Port Bypass Circuits are used in hard disk arrays constructed in Fibre Channel Arbitrated Loop (FC-AL) configurations. By using Port Bypass Circuits, hard disks may be pulled out or swapped while other disks in the array are available to the system.

A PBC consists of multiple 2:1 multiplexers daisy chained along with a CDR. Each port has two modes of operation: "disk in loop" and "disk bypassed." When the "disk in loop" mode is selected, the loop goes into and out of the disk drive at that port. For example, data goes from the HDMP-0552's TO_NODE[n]± differential output pins to the Disk Drive Transceiver IC (for example, an HDMP-263x) Rx± differential input pins. Data from the Disk Drive Transceiver IC Tx± differential output pins goes to HDMP-0552's FM_NODE[n]± differential input pins. Figure 2 and Figure 3 show connection diagrams for disk drive array applications. When the "disk bypassed" mode is selected, the disk drive is either absent or nonfunctional, and the loop bypasses the hard disk.

Multiple HDMP-0552's may be cascaded or connected to other members of the HDMP-04xx family through the FM_LOOP and TO_LOOP pins to create loops for arrays of disk drives greater than 4. See Table 3 to identify which of the 5 cells (0:4) provides FM_LOOP, TO_LOOP pins (cell connected to cable). Features

- Supports 1.0625/2.125 GBd Fibre Channel operation
- Quad PBC/CDR in one package
- CDR location determined by choice of cable input/output
- Amplitude valid detection on FM_NODE[0] input
- Data valid detection on FM_NODE[0] input
 - Run length violation detection
 - Comma detection
 - Configurable for both singleframe and multi-frame detection
- Speed select pin for 1 or 2 GBd operation
- Single REFCLK for 1 or 2 GBd operation
- CDR selectable via external pin
- Enable/disable equalizers on all inputs
- Enable/disable selected highspeed output drivers
- High speed LVPECL I/O
- Buffered line logic (BLL) outputs (no external bias resistors required)
- + 1.1 W typical power at $V_{CC} = 3.3$ V
- Advanced 0.35 µ BiCMOS technology
- 64 Pin, 10 mm, low cost plastic QFP package

Applications

- RAID, JBOD, BTS cabinets
- 1=> 1-4 serial buffer with or without CDR

CAUTION: As with all semiconductor ICs, it is advised that normal static precautions be taken in the handling and assembly of this component to prevent damage and/or degradation which may be induced by electrostatic discharge (ESD).



Combinations of Quad PBCs can be utilized to accommodate any number of hard disks. The unused cells in a quad may be bypassed with pulldown resistors on the BYPASS[n]- pins for these cells. Additional power savings possible by turning off unused output drives. Please refer to BLL output section on page 3. An HDMP-0552 can be wired as a single or double mux cell with a CDR. It may also be used as a single or double mux cell without a CDR. All TO NODE outputs of the HDMP-0552 are of equal strength. Therefore, this part may be used as a 1 = 1 - 4 buffer.

The design of HDMP-0552 allows for placement of the CDR at any location with respect to hard disk slots. For example, if BYPASS[0]pin is tied to V_{CC} and hard disk slots A to D are connected to PBC cells 1 to 4 in the same order, the CDR function is performed at entry to the HDMP-0552 (Figure 2). To achieve a CDR function at exit from the HDMP-0552, BYPASS[1] - must be tied to V_{CC} and hard disk slots A to D must be connected to PBC cells 2, 3, 4, 0 in that order (Figure 3). Table 3 shows all possible connections. In case of CDR at entry, a Signal Detect (SD) pin shows the status of the signal at the incoming cable. The recommended method of setting the BYPASS[i]- pins HIGH is to drive them with a high-impedance signal. Internal pull-up resistors force the BYPASS[i]- pins to V_{CC}.

HDMP-0552 Block Diagram

CDR

The Clock and Data Recovery (CDR) block is responsible for frequency and phase locking onto the incoming serial data stream and resampling the incoming data based on the recovered clock. An automatic locking feature allows the CDR to lock onto the input data stream without external training controls. It does this by continually frequency locking onto the reference clock (REFCLK) and then phase locking onto the input data stream. Once bit-locked, the CDR generates a high-speed sampling clock. This clock is used to sample or repeat the incoming data to produce the CDR output. The CDR jitter specifications listed in this data sheet assume an input that has been 8B/10B encoded.

Data Valid Output

The outgoing data from the CDR is checked for two types of errors. First, the data is checked for "Run Length Violations" (RLV), which are defined as a consecutive bit sequence greater than five. In addition, the data is checked for "No Comma Detected" (NCD), which is defined as no comma within a 2¹⁵ bit frame. If neither of these errors occur, the data is considered valid Fibre Channel data, and FM_NODE[0]_DV is driven HIGH.

For reporting errors, the data valid (DV) block contains a 2¹⁵bit counter to provide a frame clock. All errors are reported relative to the rising edge of this internally generated clock.

There are two LVTTL inputs for configuring the data validity checking. When MODE_DV is HIGH, the data input for the CDR comes from FM_NODE[0]. In this mode, the FM_NODE[0] input is checked for data validity. In addition, the FM_NODE[0]_DV LVTTL output can be used to drive BYPASS[0]- signal. In this configuration, when the data is invalid, the CDR output will be bypassed and the data from TO_NODE[0] will be passed on instead.

When MODE_DV is LOW, the data validity checking is still taking place on output of the CDR; however, this data may be from another input besides FM_NODE[0]. In addition, the CDR output data will always be passed on to TO_NODE[1] in this mode.

Lastly, the LVTTL input FSEL selects single versus multi-frame operation of the DV block. For example, when FSEL is LOW, the FM_NODE[0]_DV output will be driven HIGH after 2¹⁵ bits of good data. Similarly, FM_NODE[0]_DV will be driven LOW after one 2¹⁵ bit sequence containing errors. This is "single frame" operation.

When FSEL is HIGH, the DV block is operating in "multi-frame", or four frame, mode. In this mode, the FM_NODE[0]_DV will be driven HIGH only after four consecutive frames of valid data. Once HIGH, FM_NODE[0]_DV will only be driven LOW after four consecutive 2¹⁵-bit frames containing errors.

REFCLK Input and REF_RATE Control

The LVTTL REFCLK input provides a reference oscillator for frequency acquisition of the CDR. The REFCLK frequency should be 53.125 Mhz or 106.25 Mhz ±100 ppm. Set REF_RATE = 0 for a 53 Mhz and set REF_RATE = 1 for 106 MHz references. Either reference frequency can be used for both 1 GBd or 2 GBd rates.

Amplitude Valid Output

The Amplitude Valid (AV) block detects if the incoming data on FM_NODE[0]+ is valid by examining the differential amplitude of that input. The incoming data is considered valid and FM_NODE[0]_AV is driven HIGH, as long as the amplitude is greater than 200 mV (differential peak-to-peak). FM_NODE[0]_AV is driven LOW as long as the amplitude of the input signal is less than 100 mV (differential peak-to-peak). When the amplitude of the input signal is between 100 and 200 mV (differential peak-topeak), FM_NODE[0]_AV is unpredictable.

Equalizer Input

All FM_NODE[n]+ high-speed differential inputs have an equalization setting to offset the effects of skin loss and dispersion on PCBs. This function is independently controllable for each input port using the EQ_SEL and NDx (x = 0-4) pins. The default setting for the equalization is TRUE. Equalization maybe set to FAULT for individual inputs by forcing EQ_SEL low and NDx (where x = port number) low for each port that the equalization setting is desired to be false. It is a logic OR function. For instance, forcing EQ_SEL, ND2 & ND3 pins low will turn off the equalization setting at FM_NODE[2]+ and FM_NODE[3]+ while the equalization setting will remain on for ports 0, 1 and 4.

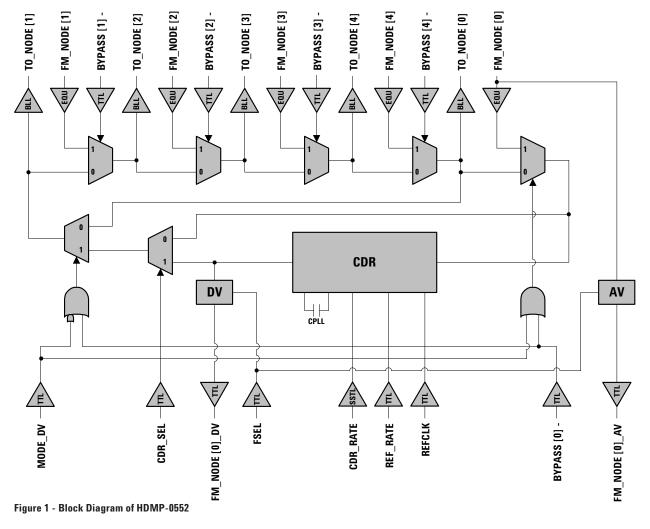
The EQ_SEL and NDx (x = 0-4) pins are LVTTL and contain internal pull-up circuitry. To force a pin low each pin should be connected to GND through a 1 k Ω resistor. Otherwise, these inputs should be left to float. In this case, the internal pull-up circuitry will force them high.

BYPASS[n]-Input

The active low BYPASS[n]- inputs control the data flow through the HDMP-0552. All BYPASS pins are LVTTL and contain internal pull-up circuitry. To bypass a port, the appropriate BYPASS[n]pin should be connected to GND through a 1 k Ω resistor. Otherwise, the BYPASS[n]inputs should be left to float. In this case, the internal pull-up circuitry will force them high.

BLL Output

All TO_NODE[n]+ high-speed differential outputs are driven by a Buffered Line Logic (BLL) circuit that has on-chip source termination. Therefore, no external bias resistors are required. The BLL outputs on the HDMP-0552 are of equal strength. Unused outputs should be turned off independently. This reduces power and reduces the potential for crosstalk effects caused by incorrect terminations. If the unused outputs are not turned off they should be differentially terminated. The value of the termination resistor should match the PCB trace differential impedance. Each output port is set to active or inactive by the OUT_SEL and NDx (x = 0.4) pins.



Output port active is the default condition. Each output port may be set to inactive by forcing OUT_SEL low and NDx (where x = port number) low. It is a logic OR function. For instance, forcing OUT_SEL, ND1 & ND4 pins low will turn off output ports TO_NODE[1]<u>+</u> and TO_NODE[4]<u>+</u> while output ports 0,2 and 3 will remain on. When an output port is off both output terminals will pull high to approximately V_{CC}. The OUT_SEL and NDx (x = 0-4) pins are LVTTL and contain internal pull-up circuitry. To force a pin low each pin should be connected to GND through a 1 k Ω resistor. Otherwise, these inputs should be left to float. In this case, the internal pull-up circuitry will force them high.

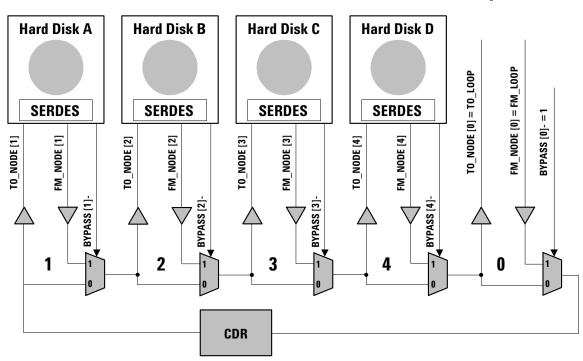


Figure 2 - Connection Diagram for CDR at First Cell

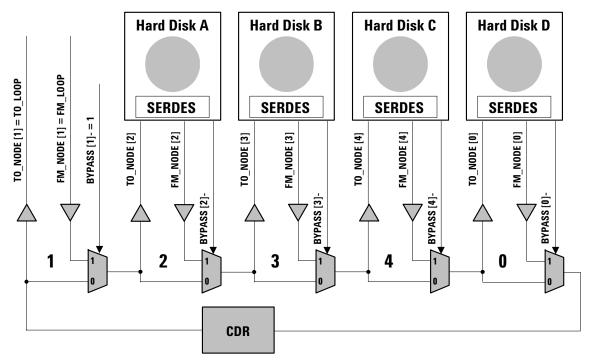


Figure 3 - Connection Diagram for CDR at Last Cell

| Pin Name | Pin | Pin Type | Pin Description |
|------------------|-----|----------|---|
| MODE_DV | 24 | I-LVTTL | Data Valid Detect Mode: To allow data valid detection, float MODE_DV |
| _ | | | HIGH. To configure chip for "CDR anywhere" capability, connect MODE_DV |
| | | | to GND through a 1 k Ω resistor. |
| FSEL | 25 | I-LVTTL | Frame Select: To configure single-frame operation of the data valid and |
| | | | amplitude valid detection circuits, connect FSEL to GND through a 1 k Ω |
| | | | resistor. To configure multi-frame (4-frame) operation of the data valid and |
| | | | amplitude valid detection circuits, float FSEL HIGH. |
| FM NODE[0] DV | 23 | 0-LVTTL | Data Valid: Indicates valid Fibre Channel Data on the FM NODE[0]± inputs |
| | 20 | O-LVIIL | when HIGH. Indicates either run length violation error or no comma detected |
| | | | when LOW. |
| FM NODE[0] AV | 59 | 0-LVTTL | Amplitude Valid: Indicates acceptable signal amplitude on the |
| FIVI_INUDE[U]_AV | 59 | U-LVIIL | |
| | 57 | | FM_NODE[0]± inputs. |
| TO_NODE[0]+ | 57 | HS_OUT | Serial Data Outputs: High-speed outputs to a hard disk drive or to a cable |
| TO_NODE[0]- | 56 | | input. |
| TO_NODE[1]+ | 32 | | |
| TO_NODE[1]- | 31 | | |
| TO_NODE[2]+ | 35 | | |
| TO_NODE[2]- | 34 | | |
| TO_NODE[3]+ | 44 | | |
| TO_NODE[3]- | 43 | | |
| TO_NODE[4]+ | 47 | | |
| TO_NODE[4]- | 46 | | |
| FM NODE[0]+ | 54 | HS_IN | Serial Data Inputs: High-speed inputs from a hard disk drive or from a cable |
| FM NODE[0]- | 53 | | output. |
| FM_NODE[1]+ | 29 | | output. |
| FM NODE[1]- | 28 | | |
| FM_NODE[2]+ | 38 | | |
| FM NODE[2]- | 37 | | |
| | 41 | | |
| FM_NODE[3]+ | | | |
| FM_NODE[3]- | 40 | | |
| FM_NODE[4]+ | 51 | | |
| FM_NODE[4]- | 50 | | |
| BYPASS[0]- | 55 | I-LVTTL | Bypass Inputs: For "disk bypassed" mode, connect BYPASS[n]- to GND |
| BYPASS[1]- | 30 | | through a 1 k Ω resistor. For "disk in loop" mode, float HIGH. |
| BYPASS[2]- | 36 | | |
| BYPASS[3]- | 42 | | |
| BYPASS[4]- | 49 | | |
| CDR_SEL | 10 | I-LVTTL | CDR Select: To configure the chip with the CDR bypassed, connect CDR_SEL |
| | | | to GND through a 1 k Ω resistor. To configure the chip with the CDR in the |
| | | | loop, float CDR_SEL HIGH. |
| CDR_RATE | 11 | I-SSTL2 | CDR Rate: To configure the chip for 1 GBd operation, connect CDR RATE to |
| — | | | GND through a 1 k Ω resistor. To configure the chip for 2 GBd operation, |
| | | | float CDR RATE HIGH. |
| REF_RATE | 12 | I-LVTTL | Reference Rate: Float REF RATE HIGH for a reference rate of 106.25 MHz |
| | 14 | | and connect REF RATE to GND via a 1 k Ω resistor for a reference rate of |
| | | | 53.125 MHz. |
| REFCLK | 14 | I-LVTTL | Reference Clock: A user-supplied clock reference used for frequency |
| NEFULK | 14 | | |
| | 10 | 0 | acquisition in the Clock and Data Recovery (CDR) circuit. |
| CPLL1 | 16 | C | Loop Filter Capacitor: A loop filter capacitor for the internal Clock and Data |
| CPLLO | 17 | С | Recovery (CDR) circuit must be connected across the CPLL1 and CPLL0 pins. |
| | | | Recommended value is 0.1 µF. |
| EQ_SEL | 61 | I-LVTTL | Equalizer Select: Allows user to select/deselect equalization on any input. |

Table 1 - Pin Definitions for HDMP-0552. Refer to Figure 4 for pin layout

| Table 1 (continue | ed) - Pin De | finitions for l | IDMP-0552. Refer to Figure 4 for pin layout |
|--------------------|--|-----------------|---|
| Pin Name | Pin | Pin Type | Pin Description |
| OUT_SEL | 60 | I-LVTTL | Output Select: Allows user to turn on/off any output driver. |
| ND0 | 64 | I-LVTTL | Node 0 Input: In combination with EQ_SEL, allows the user to select/deselect equalization on FM_NODE[0]± inputs. In combination with OUT_SEL, allows the user to turn on/off the TO_NODE[0]± output driver. Float HIGH to select Node 0, or connect to GND through a 1 k Ω resistor to deselect Node 0. |
| ND1 | 63 | I-LVTTL | Node 1 Input: In combination with EQ_SEL, allows the user to select/deselect equalization on FM_NODE[1]± inputs. In combination with OUT_SEL, allows the user to turn off/on the TO_NODE[1]± output driver. Float HIGH to select Node 1, or connect to GND through a 1 k Ω resistor to deselect Node 1. |
| ND2 | 62 | I-LVTTL | Node 2 Input: In combination with EQ_SEL, allows the user to select/deselect equalization on FM_NODE[2]± inputs. In combination with OUT_SEL, allows the user to turn off/on the TO_NODE[2]± output driver. Float HIGH to select Node 2, or connect to GND through a 1 k Ω resistor to deselect Node 2. |
| ND3 | 20 | I-LVTTL | Node 3 Input: In combination with EQ_SEL, allows the user to select/deselect equalization on FM_NODE[3]± inputs. In combination with OUT_SEL, allows the user to turn off/on the TO_NODE[3]± output driver. Float HIGH to select Node 3, or connect to GND through a 1 k Ω resistor to deselect Node 3. |
| ND4 | 21 | I-LVTTL | Node 4 Input: In combination with EQ_SEL, allows the user to select/deselect equalization on FM_NODE[4]± inputs. In combination with OUT_SEL, allows the user to turn off/on the TO_NODE[4]± output driver. Float HIGH to select Node 4, or connect to GND through a 1 k Ω resistor to deselect Node 4. |
| TDO | 2 | 0-LVTTL | JTAG |
| TDI | 3 | I-LVTTL | JTAG |
| nTRST | 4 | I-LVTTL | JTAG |
| TMS | 5 | I-LVTTL | JTAG |
| ТСК | 6 | I-LVTTL | JTAG |
| NC | 19 | NC | No Connect. |
| GND | 07 09 15 18 26 39 52 | S | Ground : Normally 0 V. |
| V _{cc} | 01 13 22 27 48 | S | Digital Power Supply pin. |
| V _{cc} A | 08 | S | Analog Power Supply pin. |
| V _{cc} HS | 33 45 58 | S S S | Cells 1 and 2 High Speed Output Pins Power Supply. Cells 3 and 4 High Speed Output Pins Power Supply. Cell 0 High Speed Output Pins Power Supply. |

| Table 1 (continued) | - Pin | Definitions f | or HDMP | -0552. Refei | r to Figure | e 4 for | pin l | layout |
|---------------------|-------|----------------------|---------|--------------|-------------|---------|-------|--------|
|---------------------|-------|----------------------|---------|--------------|-------------|---------|-------|--------|

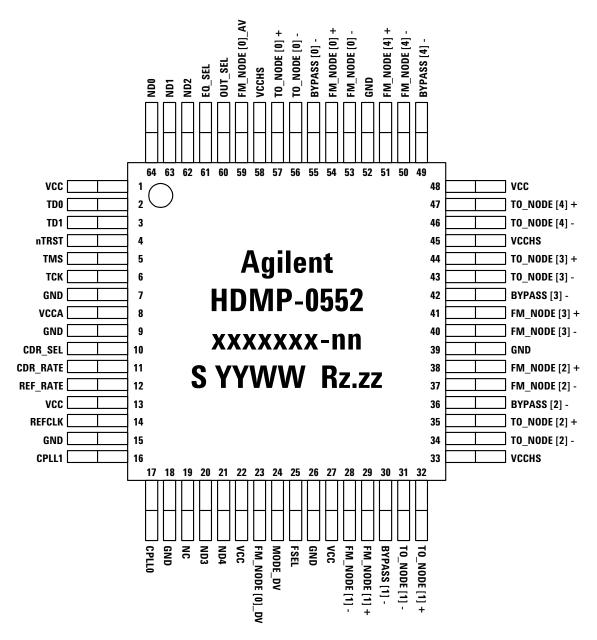




Table 2 - I/O Type Definitions

| I/O Type | Definition | | | | | | |
|----------|----------------------------------|----------------------------------|--|--|--|--|--|
| I-LVTTL | LVTTL Input | LVTTL Input | | | | | |
| 0-LVTTL | LVTTL Output | LVTTL Output | | | | | |
| HS_OUT | High Speed Output, BLL | High Speed Output, BLL | | | | | |
| HS_IN | High Speed Input | High Speed Input | | | | | |
| С | External circuit node | | | | | | |
| S | Power supply or ground | | | | | | |
| NC | No connect | No connect | | | | | |
| I-SSTL2 | SSTL2 compatible, non-terminated | SSTL2 compatible, non-terminated | | | | | |

Please refer to Figures 5 and 6 for simplified I/O diagrams.

Table 3 - Pin Connection Diagram to Achieve Desired CDR Location

| Hard Disks | Α | В | С | D | А | В | С | D | А | В | С | D | А | В | С | D | А | В | С | D |
|-------------------------|----|---|---|---|----|---|---|---|---|-----|----|---|---|---|-----|----|---|---|---|----|
| Connection to PBC cells | 1 | 2 | 3 | 4 | 0 | 1 | 2 | 3 | 4 | 0 | 1 | 2 | 3 | 4 | 0 | 1 | 2 | 3 | 4 | 0 |
| CDR position (x) | хA | В | С | D | Аx | В | С | D | А | B > | ĊC | D | А | В | С > | (D | А | В | С | Dх |
| Cell connected to Cable | 0 | | | | 4 | | | | 3 | | | | 2 | | | | 1 | | | |

x denotes CDR position with respect to hard disks. For example A x B C D means the CDR is between disk A and disk B.

HDMP-0552 Electrical Specifications

Absolute Maximum Ratings

 $Ta = +25^{\circ}C$, except as specified.

Operation in excess of any of these conditions may result in permanent damage to this device.

| Symbol | Parameter | Units | Minimum | Maximum |
|------------|----------------------|-------|---------|---------|
| VCC | Supply Voltage | V | -0.7 | 4.0 |
| VIN, LVTTL | LVTTL Input Voltage | V | -0.7 | 5.0 |
| VIN,HS_IN | HS_IN Input Voltage | V | 2.0 | VCC |
| IO,LVTTL | LVTTL Output Current | mA | | +13 |
| Tstg | Storage Temperature | C° | -65 | +150 |
| Tj | Junction Temperature | J° | 0 | +125 |

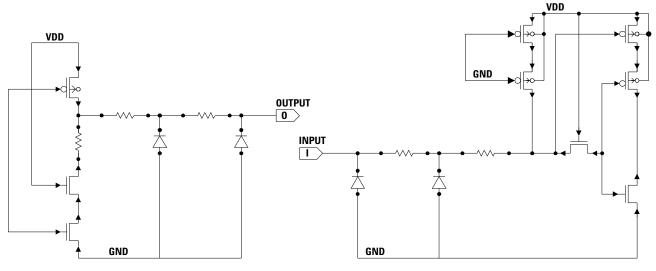


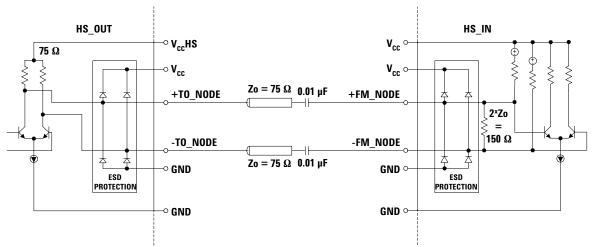
Figure 5 - Simplified Digital I/O Circuit Diagrams

Guaranteed Operating Rates

 $Ta=0^\circ\text{C}~$ to $Tc=+80^\circ\text{C}$, VCC = 3.15 V to 3.45 V

Serial Clock Rate

| FC (IVIBd) | |
|------------|---------|
| Minimum | Maximum |
| 1,040 | 1,080 |
| 2,080 | 2,160 |



NOTE: HS_IN INPUTS SHOULD NEVER BE CONNECTED TO GROUND AS PERMANENT DAMAGE TO THE DEVICE MAY RESULT.

Figure 6 - O-BLL and I-BLL Simplified Circuit Schematic

Clock and Data Recovery Circuit (CDR) Reference Clock Requirements

 $Ta = 0^{\circ}C$ to $Tc = +80^{\circ}C$, VCC = 3.15 V to 3.45 V

| Symbol | Parameter | Units | Minimum Typical | Maximum |
|--------|----------------------------------|-------|-----------------|---------|
| f | Nominal Frequency (REF_RATE = 1) | MHz | 106.25 | |
| f | Nominal Frequency (REF_RATE = 0) | MHz | 53.125 | |
| Ftol | Frequency Tolerance | ppm | -100 | +100 |
| Symm | Symmetry (duty cycle) | % | 40 | 60 |

DC Electrical Specifications

 $Ta=0^\circ C$ to $Tc=+80^\circ C$, VCC=3.15 V to 3.45 V

| Symbol | Parameter | Units | Minimum | Typical | Maximum |
|-------------------------|---|-------|---------|---------|---------|
| VIH ¹ ,LVTTL | LVTTL Input High Voltage Range | V | 2.0 | | Vcc |
| VIL,LVTTL | LVTTL Input Low Voltage Range | V | 0 | | 0.8 |
| VOH ¹ ,LVTTL | LVTTL Output High Voltage Range, IOH = -400 uA | V | 2.2 | | Vcc |
| VOL,LVTTL | LVTTL Output Low Voltage Level, IOL = 1 mA | V | 0 | | 0.6 |
| IIH,LVTTL | Input High Current (Magnitude), VIN = 2.4 V, VCC = 3.45 V | uA | 0 | 5 | 40 |
| IIL,LVTTL | Input Low Current (Magnitude), VIN = 0.4 V, VCC = 3.45 V | uA | 0 | 65 | 300 |
| ICC | Total Supply Current, Ta = +25°C | mA | | 320 | |

Note: 1. LVTTL I/Os 5 V tolerant.

AC Electrical Specifications

| Symbol | Parameter | Units | Minimum | Typical | Maximum |
|--------------------------|--|-------|---------|---------|---------|
| tdelay1 | Total Loop Latency from FM_NODE[0] to TO_NODE[0] | ns | | 1.5 | 4.0 |
| tdelay2 | Per Cell Latency from FM_NODE[x] to TO_NODE[x+1] | ns | | 0.4 | 0.8 |
| tr,LVTTLin | Input LVTTL Rise Time Requirement, 0.8 V to 2.0 V | ns | | 2 | |
| tf,LVTTLin | Input LVTTL Fall Time Requirement, 2.0 V to 0.8 V | ns | | 2 | |
| tr, LVTTLout | Output LVTTL Rise Time Range, 0.8 V to 2.0 V, 10 pF Load | ns | | 1.5 | |
| tf, LVTTLout | Output LVTTL Fall Time Range, 2.0 V to 0.8 V, 10 pF Load | ns | | 2.0 | |
| trs ² ,HS_0UT | HS_OUT Single-Ended Rise Time | ps | 44 | 65 | 110 |
| tfs ² ,HS_0UT | HS_OUT Single-Ended Fall Time | ps | 44 | 65 | 110 |
| trd ² ,HS_OUT | HS_OUT Differential Rise Time | ps | 44 | 65 | 110 |
| tfd ² ,HS_OUT | HS_OUT Differential Fall Time | ps | 44 | 65 | 110 |
| VIP,HS_IN | HS_IN Input Peak to Peak Required Differential Voltage Range | mV | 200 | | 2000 |
| VOP,HS_OUT | HS_OUT Output Pk-Pk Diff. Voltage Range (Zo = 75 Ω) | mV | 1100 | 1400 | 2000 |

 $Ta = 0^{\circ}C$ to $Tc = +80^{\circ}C$, VCC = 3.15 V to 3.45 V

Note: 2. Measured from 20% to 80% levels with trace length 3", Fr-4 board, Zo= 50 ohms and a 50 ohm and 200 fF termination. Please refer to Figure 6 for simplified circuit schematic.

Power Dissipation and Thermal Resistance

 $Ta = 0^{\circ}C$ to $Tc = +80^{\circ}C$, VCC = 3.15 V to 3.45 V

| Symbol | Parameter | Units | Typical | Maximum |
|--------|--------------------------------------|-------|---------|---------|
| PD | Power Dissipation | W | 1.1 | 1.28 |
| hetajc | Thermal Resistance, Junction to Case | °C/W | 2.5 | |

Output Jitter Characteristics

 $Ta=0^\circ C$ to $Tc=+80^\circ C$, VCC=3.15 V to 3.45 V

| Symbol | Parameter | Units | Typical |
|--------|--|-------|---------|
| RJ | Random Jitter at TO_NODE pins (1 sigma rms) | ps | 3.5 |
| DJ | Deterministic Jitter at TO_NODE pins (pk-pk) | ps | 10 |

Please refer to Figures 8 and 9 for jitter measurement setup information.

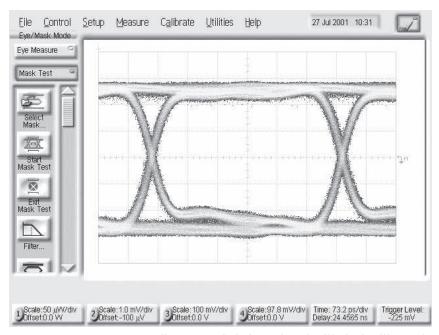


Figure 7 - Eye Diagram obtained differentially at 2.125 GBd FROM NODE(0) TO NODE(2) with 50 Ω termination

Locking Characteristics

 $Ta=0^\circ C$ to $Tc=+80^\circ C$, VCC=3.15 V to 3.45 V

| Parameter | Units | Maximum | | |
|----------------------------|-------|---------|--|--|
| Bit Sync Time (phase lock) | bits | 2500 | | |
| Frequency Lock at Powerup | μs | 500 | | |

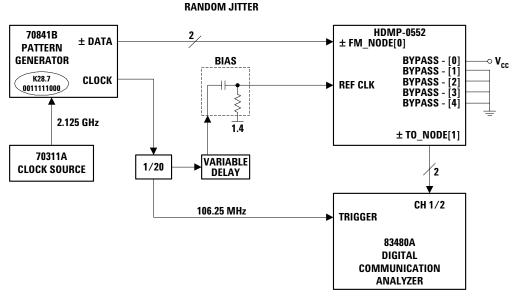
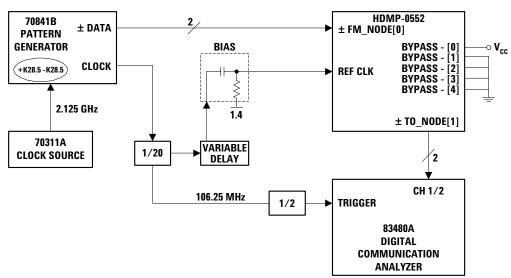


Figure 8 - Setup for Measurement of Random Jitter



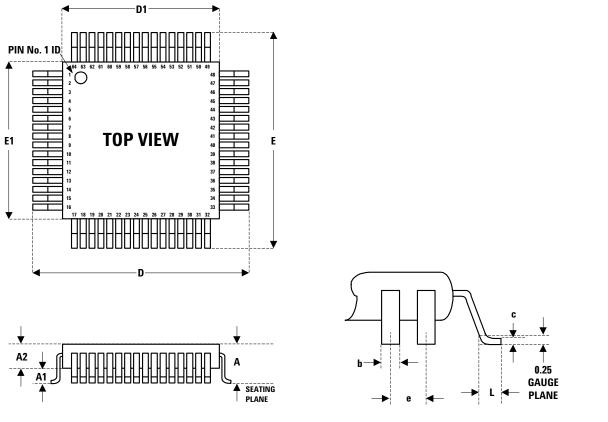
DETERMINISTIC JITTER

Figure 9 - Setup for Measurement of Deterministic Jitter

Package Information

| ltem | Details Plastic | | | |
|------------------------|---------------------------|--|--|--|
| Package Material | | | | |
| Lead Finish Material | 85% Tin, 15% Lead | | | |
| Lead Finish Thickness | 300-800 micro-inches | | | |
| Lead Skew | 0.08 mm maximum | | | |
| Lead Coplanarity | 0.08 mm maximum | | | |
| (Seating Plane Method) | | | | |

Mechanical Dimensions



| Dimensional Parameter (millimeters) | Α | A1 | A2 | D/E | D1/E1 | L | b | C | e |
|---|------|------|-----------------|-------|-------|-----------------|-------|------|-------|
| Value | 2.45 | 0.25 | 2.00 | 13.20 | 10.00 | 0.88 | 0.22 | 0.17 | 0.50 |
| Tolerance | MAX | MIN | +0.10, -0.05 | ±0.25 | ±0.10 | +0.15, -0.10 | ±0.05 | MAX | BASIC |

Figure 10 - HDMP-0552 Package Drawing

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